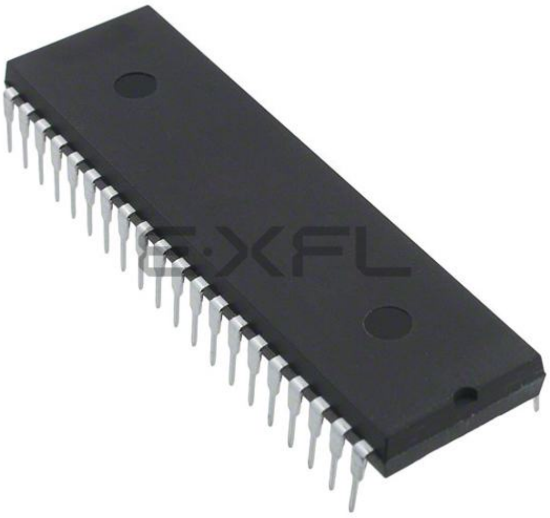
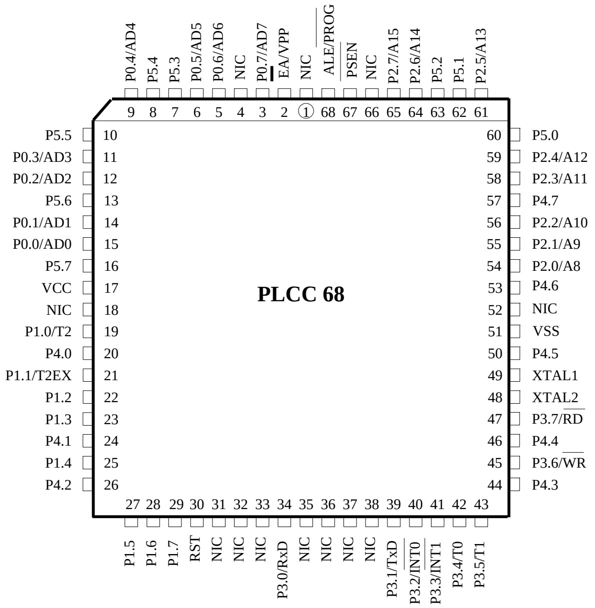


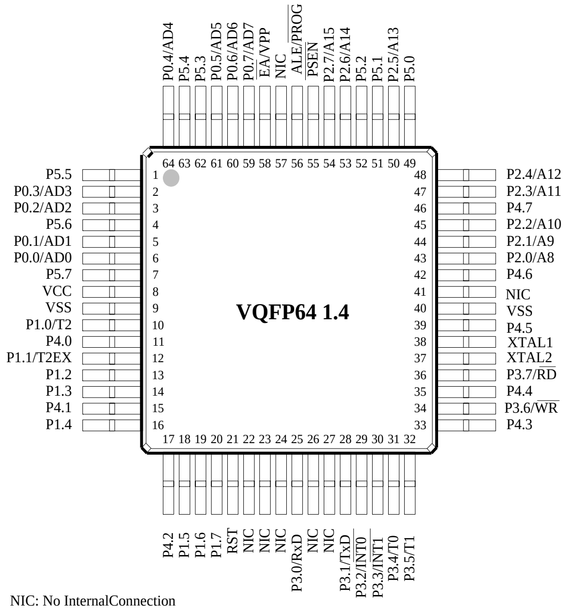
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/30MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	16KB (16K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIL
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c51rb2-vca





NIC: No InternalConnection

5.1. Pin Description for 64/68 pin Packages

Port 4 and Port 5 are 8-bit bidirectional I/O ports with internal pull-ups. Pins that have 1 written to them are pulled high by the internal pull ups and can be used as inputs.

As inputs, pins that are externally pulled low will source current because of the internal pull-ups.

Refer to the previous pin description for other pins.

Table 2. 64/68 Pin Packages Configuration

	PLCC68	SQUARE VQFP64 1.4
VSS	51	9/40
VCC	17	8
P0.0	15	6
P0.1	14	5
P0.2	12	3
P0.3	11	2
P0.4	9	64
P0.5	6	61
P0.6	5	60
P0.7	3	59
P1.0	19	10
P1.1	21	12
P1.2	22	13
P1.3	23	14
P1.4	25	16
P1.5	27	18
P1.6	28	19
P1.7	29	20
P2.0	54	43
P2.1	55	44
P2.2	56	45
P2.3	58	47
P2.4	59	48
P2.5	61	50
P2.6	64	53
P2.7	65	54
P3.0	34	25
P3.1	39	28

6.2. Dual Data Pointer Register Ddptr

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 (See Table 4.) that allows the program code to switch between them (Refer to Figure 3).

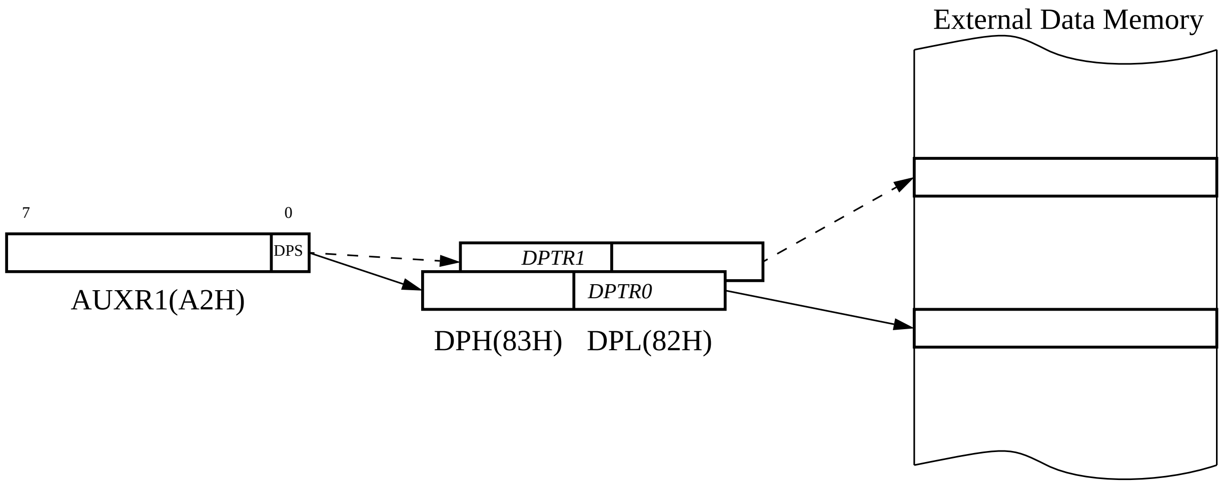


Figure 3. Use of Dual Pointer

Table 4. AUXR1: Auxiliary Register 1

AUXR1 Address 0A2H		-	-	-	-	GF3	-	-	DPS
	Reset value	X	X	X	X	0	X	X	0

Symbol	Function	
-	Not implemented, reserved for future use.[a]	
DPS	Data Pointer Selection.	
	DPS	**Operating Mode**
	0	DPTR0 Selected
	1	DPTR1 Selected
GF3	This bit is a general purpose user flag[b].	

a. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new feature. In that case, the reset value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

b. GF3 will not be available on first version of the RC devices.

Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a ’source’ pointer and the other one as a "destination" pointer.

6.5.1. PCA Capture Mode

To use one of the PCA modules in the capture mode either one or both of the CCAPM bits CAPN and CAPP for that module must be set. The external CEX input for the module (on port 1) is sampled for a transition. When a valid transition occurs the PCA hardware loads the value of the PCA counter registers (CH and CL) into the module's capture registers (CCAPnL and CCAPnH). If the CCFn bit for the module in the CCON SFR and the ECCFn bit in the CCAPMn SFR are set then an interrupt will be generated (Refer to Figure 9).

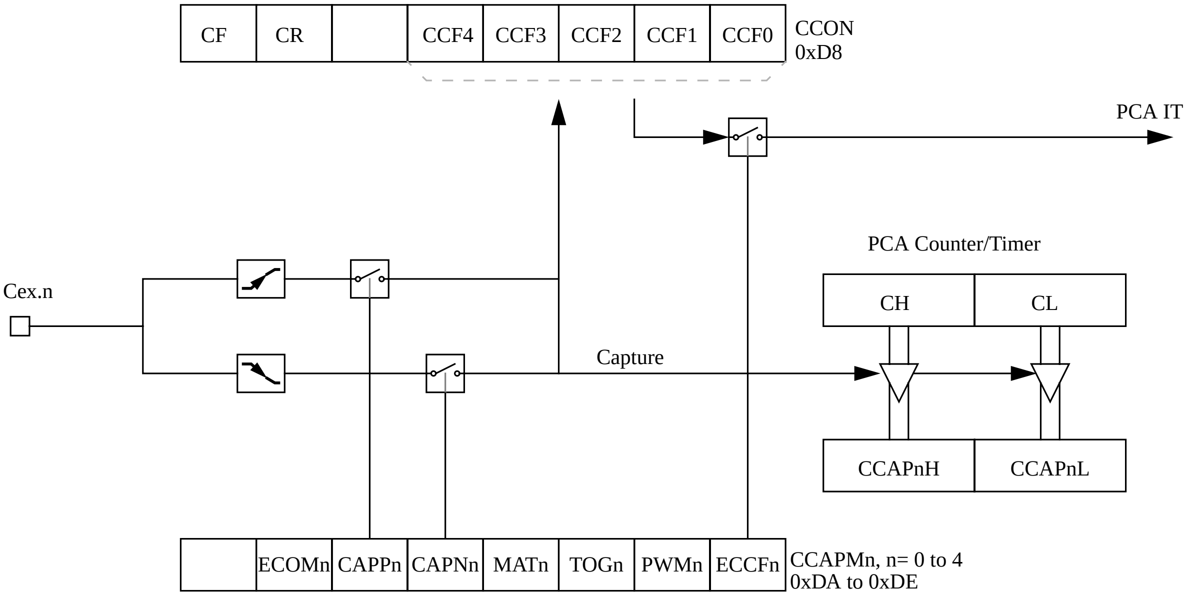


Figure 9. PCA Capture Mode

6.5.2. 16-bit Software Timer / Compare Mode

The PCA modules can be used as software timers by setting both the ECOM and MAT bits in the modules CCAPMn register. The PCA timer will be compared to the module's capture registers and when a match occurs an interrupt will occur if the CCFn (CCON SFR) and the ECCFn (CCAPMn SFR) bits for the module are both set (See Figure 10).

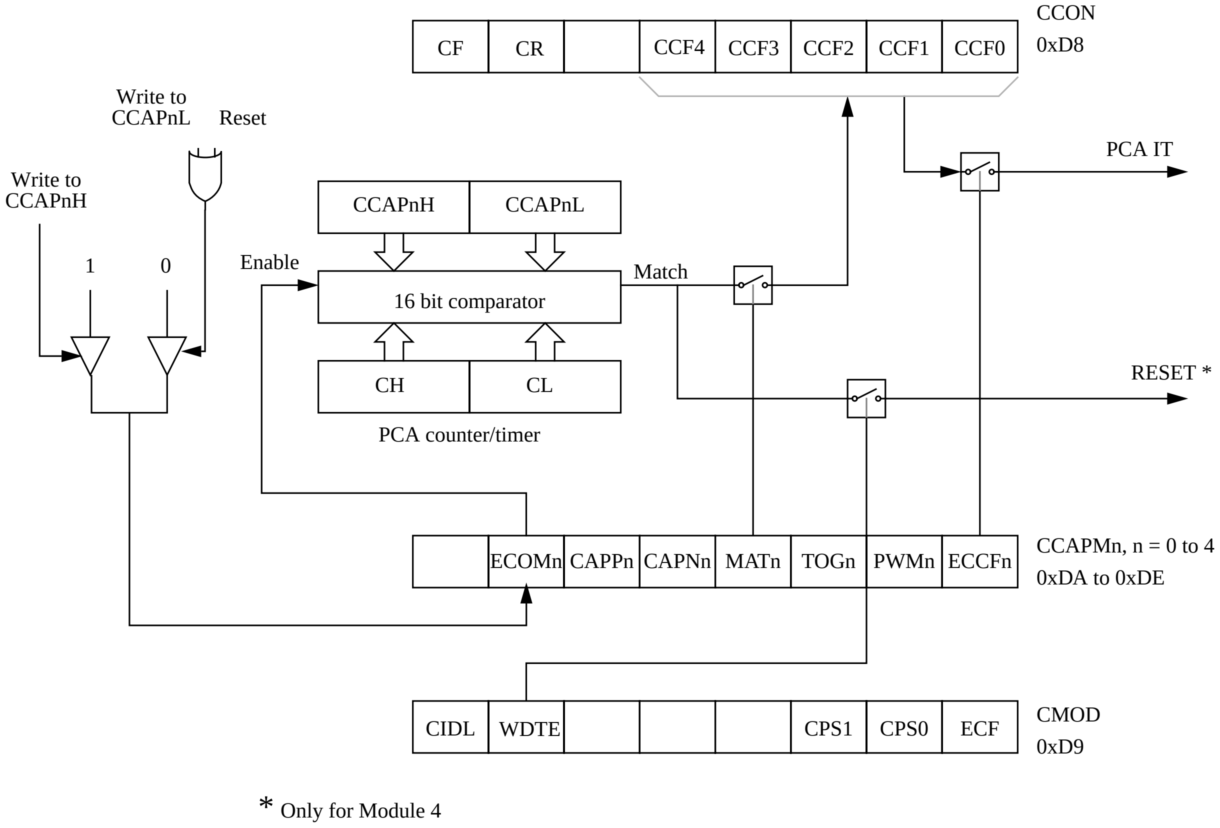


Figure 10. PCA Compare Mode and PCA Watchdog Timer

Before enabling ECOM bit, CCAPnL and CCAPnH should be set with a non zero value, otherwise an unwanted match could happen. Writing to CCAPnH will set the ECOM bit.

Once ECOM set, writing CCAPnL will clear ECOM so that an unwanted match doesn’t occur while modifying the compare value. Writing to CCAPnH will set ECOM. For this reason, user software should write CCAPnL first, and then CCAPnH. Of course, the ECOM bit can still be controlled by accessing to CCAPMn register.

6.5.3. High Speed Output Mode

In this mode the CEX output (on port 1) associated with the PCA module will toggle each time a match occurs between the PCA counter and the module's capture registers. To activate this mode the TOG, MAT, and ECOM bits in the module's CCAPMn SFR must be set (See Figure 11).

A prior write must be done to CCAPnL and CCAPnH before writing the ECOMn bit.

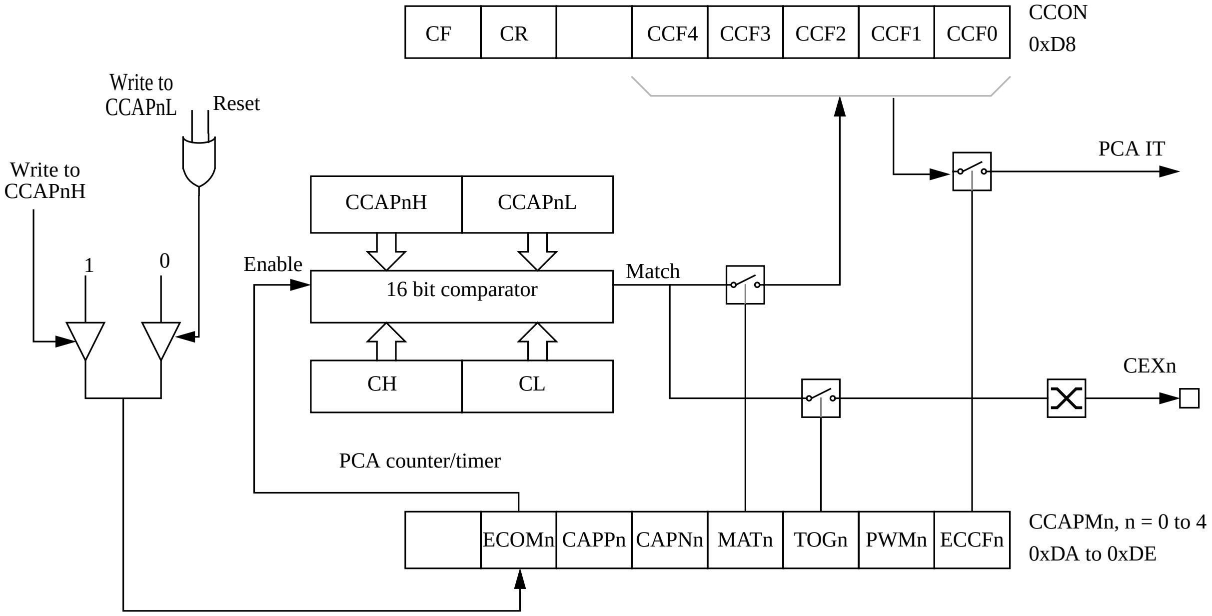


Figure 11. PCA High Speed Output Mode

Before enabling ECOM bit, CCAPnL and CCAPnH should be set with a non zero value, otherwise an unwanted match could happen.

Once ECOM set, writing CCAPnL will clear ECOM so that an unwanted match doesn't occur while modifying the compare value. Writing to CCAPnH will set ECOM. For this reason, user software should write CCAPnL first, and then CCAPnH. Of course, the ECOM bit can still be controlled by accessing to CCAPMn register.

6.6.3. Given Address

Each device has an individual address that is specified in SADDR register; the SADEN register is a mask byte that contains don’t-care bits (defined by zeros) to form the device’s given address. The don’t-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed. To address a device by its individual address, the SADEN mask byte must be `1111 1111b`.
For example:

```
          SADDR     0101 0110b
          SADEN     1111 1100b
          Given     0101 01XXb
```

The following is an example of how to use given addresses to address different slaves:

```
Slave A:  SADDR     1111 0001b
          SADEN     1111 1010b
          Given     1111 0X0Xb

Slave B:  SADDR     1111 0011b
          SADEN     1111 1001b
          Given     1111 0XX1b

Slave C:  SADDR     1111 0010b
          SADEN     1111 1101b
          Given     1111 00X1b
```

The SADEN byte is selected so that each slave may be addressed separately.
For slave A, bit 0 (the LSB) is a don’t-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g. `1111 0000b`).
For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don’t care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. `1111 0011b`).
To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. `1111 0001b`).

6.6.4. Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don’t-care bits, e.g.:

```
          SADDR          0101 0110b
          SADEN          1111 1100b
Broadcast =SADDR OR SADEN  1111 111Xb
```

The use of don’t-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:  SADDR     1111 0001b
          SADEN     1111 1010b
          Broadcast 1111 1X11b,

Slave B:  SADDR     1111 0011b
          SADEN     1111 1001b
          Broadcast 1111 1X11B,

Slave C:  SADDR=    1111 0010b
          SADEN     1111 1101b
          Broadcast 1111 1111b
```

For slaves A and B, bit 2 is a don’t care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send and address FBh.

6.7. Interrupt System

The TS80C51Rx2 has a total of 7 interrupt vectors: two external interrupts ($\overline{INT0}$ and $\overline{INT1}$), three timer interrupts (timers 0, 1 and 2), the serial port interrupt and the PCA global interrupt. These interrupts are shown in Figure 16.

WARNING: Note that in the first version of RC devices, the PCA interrupt is in the lowest priority. Thus the order in $\overline{INT0}$, TF0, $\overline{INT1}$, TF1, RI or TI, TF2 or EXF2, PCA.

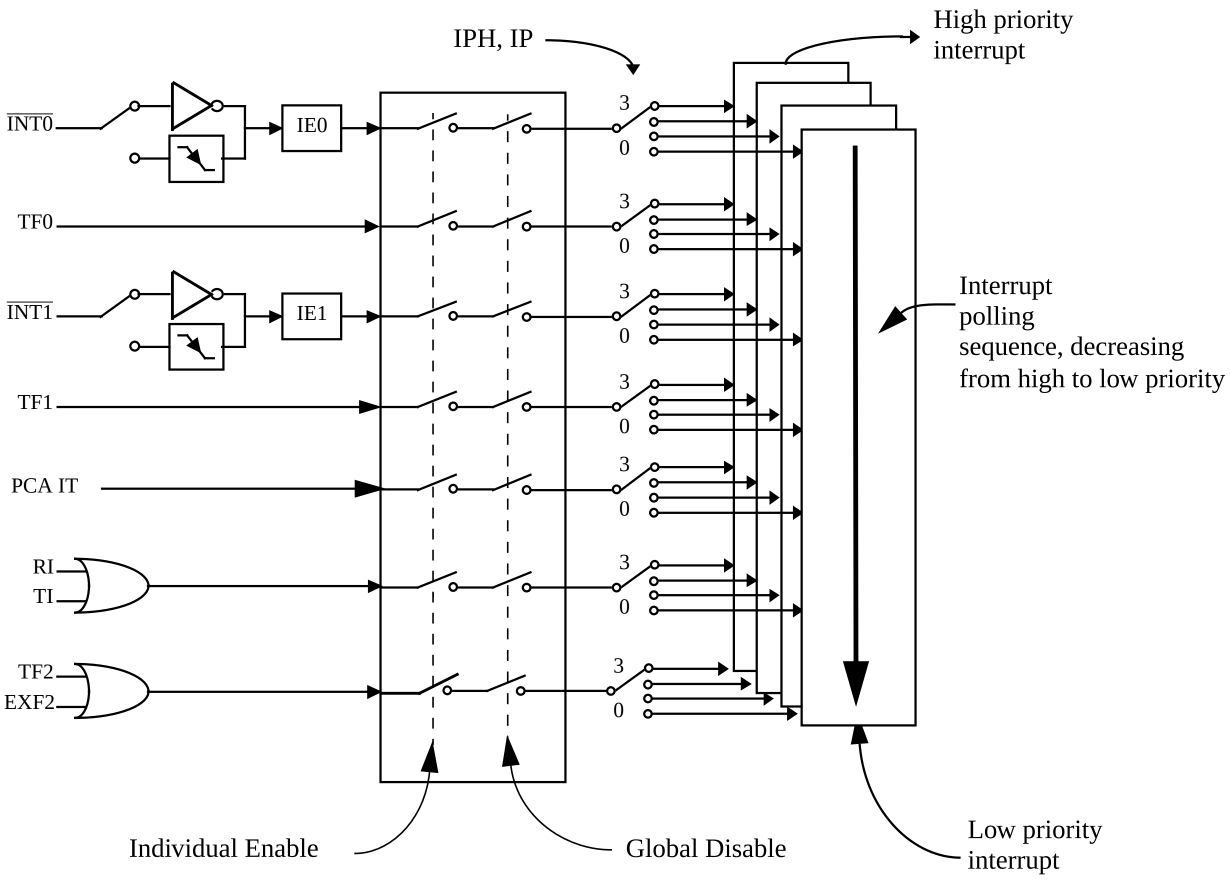


Figure 16. Interrupt Control System

Each of the interrupt sources can be individually enabled or disabled by setting or clearing a bit in the Interrupt Enable register (See Table 19.). This register also contains a global disable bit, which must be cleared to disable all interrupts at once.

Each interrupt source can also be individually programmed to one out of four priority levels by setting or clearing a bit in the Interrupt Priority register (See Table 20.) and in the Interrupt Priority High register (See Table 21.). shows the bit values and priority levels associated with each combination.

The PCA interrupt vector is located at address 0033H. All other vector addresses are the same as standard C52 devices.

Table 21. IPH Register

IPH - Interrupt Priority High Register (B7h)

7	6	5	4	3	2	1	0
-	PPCH	PT2H	PSH	PT1H	PX1H	PT0H	PX0H

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	PPCH	**PCA interrupt priority bit high.** PPCH PPC Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
5	PT2H	**Timer 2 overflow interrupt Priority High bit** PT2H PT2 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
4	PSH	**Serial port Priority High bit** PSH PS Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
3	PT1H	**Timer 1 overflow interrupt Priority High bit** PT1H PT1 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
2	PX1H	**External interrupt 1 Priority High bit** PX1H PX1 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
1	PT0H	**Timer 0 overflow interrupt Priority High bit** PT0H PT0 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
0	PX0H	**External interrupt 0 Priority High bit** PX0H PX0 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest

Reset Value = X000 0000b
Not bit addressable

6.8. Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely : the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

6.9. Power-Down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 17., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{\text{INT0}}$ and $\overline{\text{INT1}}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.
Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 17. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.
Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C51Rx2 into power-down mode.

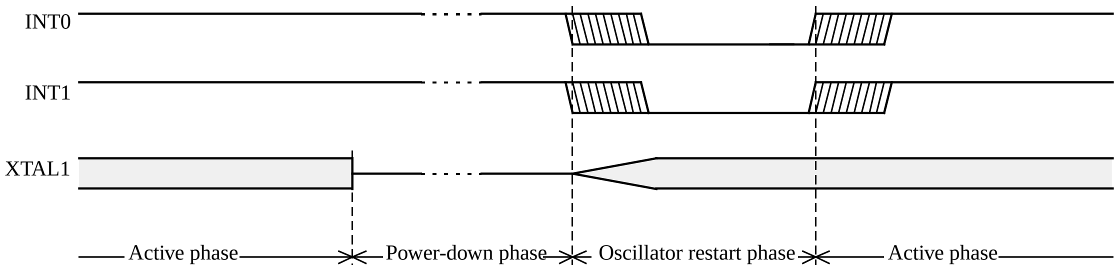


Figure 17. Power-Down Exit Waveform

Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does no affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.
NOTE: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

6.10. Hardware Watchdog Timer

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upset. The WDT consists of a 14-bit counter and the WatchDog Timer ReSeT (WDTRST) SFR. The WDT is by default disabled from exiting reset. To enable the WDT, user must write 01EH and 0E1H in sequence to the WDTRST, SFR location 0A6H. When WDT is enabled, it will increment every machine cycle while the oscillator is running and there is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST-pin.

6.10.1. Using the WDT

To enable the WDT, user must write 01EH and 0E1H in sequence to the WDTRST, SFR location 0A6H. When WDT is enabled, the user needs to service it by writing to 01EH and 0E1H to WDTRST to avoid WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH) and this will reset the device. When WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycle. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write only register. The WDT counter cannot be read or written. When WDT overflows, it will generate an output RESET pulse at the RST-pin. The RESET pulse duration is 96 x T_{OSC} , where $T_{OSC} = 1/F_{OSC}$. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

To have a more powerful WDT, a 2^7 counter has been added to extend the Time-out capability, ranking from 16ms to 2s @ F_{OSC} = 12MHz. To manage this feature, refer to WDTPRG register description, Table 24. (SFR0A7h).

Table 23. WDTRST Register

WDTRST Address (0A6h)

	7	6	5	4	3	2	1
Reset value	X	X	X	X	X	X	X

Write only, this SFR is used to reset/enable the WDT by writing 01EH then 0E1H in sequence.

6.12. Power-Off Flag

The power-off flag allows the user to distinguish between a “cold start” reset and a “warm start” reset.

A cold start reset is the one induced by V_{CC} switch-on. A warm start reset occurs while V_{CC} is still applied to the device and could be generated for example by an exit from power-down.

The power-off flag (POF) is located in PCON register (See Table 26.). POF is set by hardware when V_{CC} rises from 0 to its nominal voltage. The POF can be set or cleared by software allowing the user to determine the type of reset.

The POF value is only relevant with a Vcc range from 4.5V to 5.5V. For lower Vcc value, reading POF bit will return indeterminate value.

Table 26. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0
SMOD1	**SMOD0**	**-**	**POF**	**GF1**	**GF0**	**PD**	**IDL**

Bit Number	Bit Mnemonic	Description
7	SMOD1	**Serial port Mode bit 1** Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	**Serial port Mode bit 0** Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	POF	**Power-Off Flag** Clear to recognize next reset type. Set by hardware when V_{CC} rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	**Power-Down mode bit** Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	**Idle mode bit** Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b
Not bit addressable

7. TS83C51RB2/RC2/RD2 ROM

7.1. ROM Structure

The TS83C51RB2/RC2/RD2 ROM memory is divided in three different arrays:

- the code array: . . . . 16/32/64 Kbytes.
- the encryption array: . . . . 64 bytes.
- the signature array: . . . . 4 bytes.

7.2. ROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

7.2.1. 7.2.1. Encryption Array

Within the ROM array are 64 bytes of encryption array that are initially unprogrammed (all FF’s). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR’ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

7.2.2. Program Lock Bits

The lock bits when programmed according to Table 28. will provide different level of protection for the on-chip code and data.

Table 28. Program Lock bits

Program Lock Bits				Protection description
Security level	LB1	LB2	LB3	
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset.
3	U	P	U	Same as level 1+ Verify disable. This security level is only available for 51RDX2 devices.

U: unprogrammed
P: programmed

7.2.3. Signature bytes

The TS83C51RB2/RC2/RD2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 8.3.

7.2.4. Verify Algorithm

Refer to 8.3.4.

8. TS87C51RB2/RC2/RD2 EPROM

8.1. EPROM Structure

The TS87C51RB2/RC2/RD2 EPROM is divided in two different arrays:

- the code array: . . . . .16/32/64 Kbytes.
- the encryption array: . . . . 64 bytes.

In addition a third non programmable array is implemented:

- the signature array: . . . . .4 bytes.

8.2. EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

8.2.1. Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF’s). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR’ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

8.2.2. Program Lock Bits

The three lock bits, when programmed according to Table 29.8.2.3. , will provide different level of protection for the on-chip code and data.

Table 29. Program Lock bits

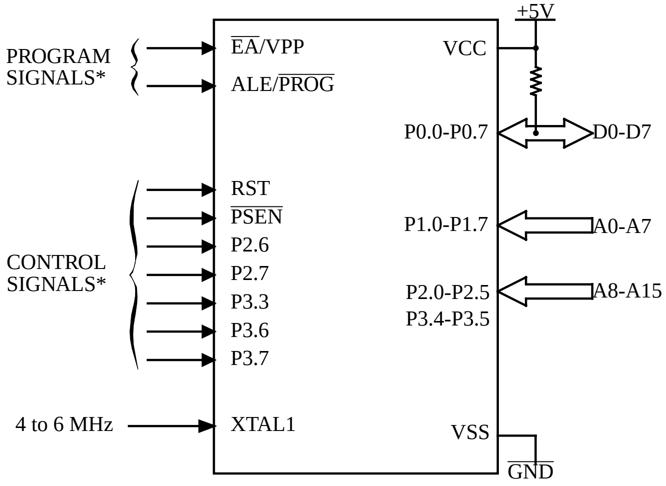
Program Lock Bits				Protection description
Security level	**LB1**	**LB2**	**LB3**	
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	P	U	Same as 2, also verify is disabled.
4	U	U	P	Same as 3, also external execution is disabled.

U: unprogrammed,
P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.

8.2.3. Signature bytes

The TS87C51RB2/RC2/RD2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 8.3.



* See Table 31. for proper value on these inputs

Figure 18. Set-Up Modes Configuration

8.3.3. Programming Algorithm

The Improved Quick Pulse algorithm is based on the Quick Pulse algorithm and decreases the number of pulses applied during byte programming from 25 to 1.

To program the TS87C51RB2/RC2/RD2 the following sequence must be exercised:

- Step 1: Activate the combination of control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Input the appropriate data on the data lines.
- Step 4: Raise $\overline{EA}$/VPP from VCC to VPP (typical 12.75V).
- Step 5: Pulse ALE/$\overline{PROG}$ once.
- Step 6: Lower $\overline{EA}$/VPP from VPP to VCC

Repeat step 2 through 6 changing the address and data for the entire array or until the end of the object file is reached (See Figure 19.).

8.3.4. Verify algorithm

Code array verify must be done after each byte or block of bytes is programmed. In either case, a complete verify of the programmed array will ensure reliable programming of the TS87C51RB2/RC2/RD2.

P 2.7 is used to enable data output.

To verify the TS87C51RB2/RC2/RD2 code the following sequence must be exercised:

- Step 1: Activate the combination of program and control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Read data on the data lines.

Repeat step 2 through 3 changing the address for the entire array verification (See Figure 19.)

The encryption array cannot be directly verified. Verification of the encryption array is done by observing that the code array is well encrypted.

9. Signature Bytes

The TS83/87C51RB2/RC2/RD2 has four signature bytes in location 30h, 31h, 60h and 61h. To read these bytes follow the procedure for EPROM verify but activate the control lines provided in Table 31. for Read Signature Bytes. Table 31. shows the content of the signature byte for the TS87C51RB2/RC2/RD2.

Table 31. Signature Bytes Content

Location	Contents	Comment
30h	58h	Manufacturer Code: Atmel Wireless & Microcontrollers
31h	57h	Family Code: C51 X2
60h	7Ch	Product name: TS83C51RD2
60h	FCh	Product name: TS87C51RD2
60h	37h	Product name: TS83C51RC2
60h	B7h	Product name: TS87C51RC2
60h	3Bh	Product name: TS83C51RB2
60h	BBh	Product name: TS87C51RB2
61h	FFh	Product revision number

10.3. DC Parameters for Standard Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

Table 32. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5$^{(6)}$			0.3 0.45 1.0	V V V	I_{OL} = 100 µA$^{(4)}$ I_{OL} = 1.6 mA$^{(4)}$ I_{OL} = 3.5 mA$^{(4)}$
V_{OL1}	Output Low Voltage, port 0 $^{(6)}$			0.3 0.45 1.0	V V V	I_{OL} = 200 µA$^{(4)}$ I_{OL} = 3.2 mA$^{(4)}$ I_{OL} = 7.0 mA$^{(4)}$
V_{OL2}	Output Low Voltage, ALE, $\overline{PSEN}$			0.3 0.45 1.0	V V V	I_{OL} = 100 µA$^{(4)}$ I_{OL} = 1.6 mA$^{(4)}$ I_{OL} = 3.5 mA$^{(4)}$
V_{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -10 µA I_{OH} = -30 µA I_{OH} = -60 µA V_{CC} = 5 V ± 10%
V_{OH1}	Output High Voltage, port 0	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -200 µA I_{OH} = -3.2 mA I_{OH} = -7.0 mA V_{CC} = 5 V ± 10%
V_{OH2}	Output High Voltage,ALE, $\overline{PSEN}$	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -100 µA I_{OH} = -1.6 mA I_{OH} = -3.5 mA V_{CC} = 5 V ± 10%
R_{RST}	RST Pulldown Resistor	50	90 $^{(5)}$	200	kΩ	
I_{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	µA	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	µA	0.45 V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	µA	Vin = 2.0 V
C_{IO}	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T_A = 25°C
I_{PD}	Power Down Current		20 $^{(5)}$	50	µA	2.0 V < V_{CC} < 5.5 V$^{(3)}$
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: $^{(7)}$			1 + 0.4 Freq (MHz) @12MHz 5.8 @16MHz 7.4	mA	V_{CC} = 5.5 V$^{(1)}$

10.5.4. External Data Memory Characteristics

Table 39. Symbol Description

Symbol	Parameter
T_{RLRH}	$\overline{RD}$ Pulse Width
T_{WLWH}	$\overline{WR}$ Pulse Width
T_{RLDV}	$\overline{RD}$ to Valid Data In
T_{RHDX}	Data Hold After $\overline{RD}$
T_{RHDZ}	Data Float After $\overline{RD}$
T_{LLDV}	ALE to Valid Data In
T_{AVDV}	Address to Valid Data In
T_{LLWL}	ALE to $\overline{WR}$ or $\overline{RD}$
T_{AVWL}	Address to $\overline{WR}$ or $\overline{RD}$
T_{QVWX}	Data Valid to $\overline{WR}$ Transition
T_{QVWH}	Data set-up to $\overline{WR}$ High
T_{WHQX}	Data Hold After $\overline{WR}$
T_{RLAZ}	$\overline{RD}$ Low to Address Float
T_{WHLH}	$\overline{RD}$ or $\overline{WR}$ High to ALE high

10.5.6. External Data Memory Read Cycle

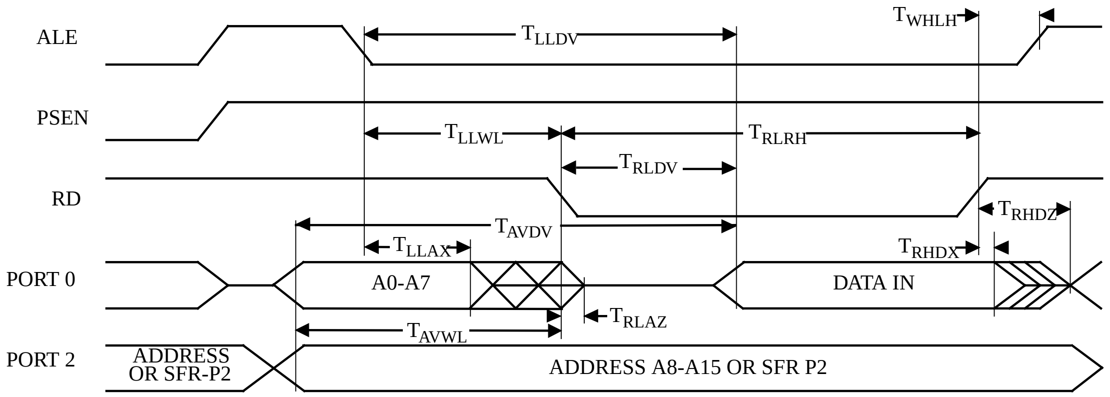


Figure 27. External Data Memory Read Cycle

10.5.7. Serial Port Timing - Shift Register Mode

Table 42. Symbol Description

Symbol	Parameter
T_{XLXL}	Serial port clock cycle time
T_{QVHX}	Output data set-up to clock rising edge
T_{XHQX}	Output data hold after clock rising edge
T_{XHDX}	Input data hold after clock rising edge
T_{XHDV}	Clock rising edge to input data valid

Table 43. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{XLXL}	300		200		300		300		400		ns
T_{QVHX}	200		117		200		200		283		ns
T_{XHQX}	30		13		30		30		47		ns
T_{XHDX}	0		0		0		0		0		ns
T_{XHDV}		117		34		117		117		200	ns

For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OL}/I_{OH} \geq \pm$ 20mA.

10.5.15. Clock Waveforms

Valid in normal clock mode. In X2 mode XTAL2 signal must be changed to XTAL2 divided by two.

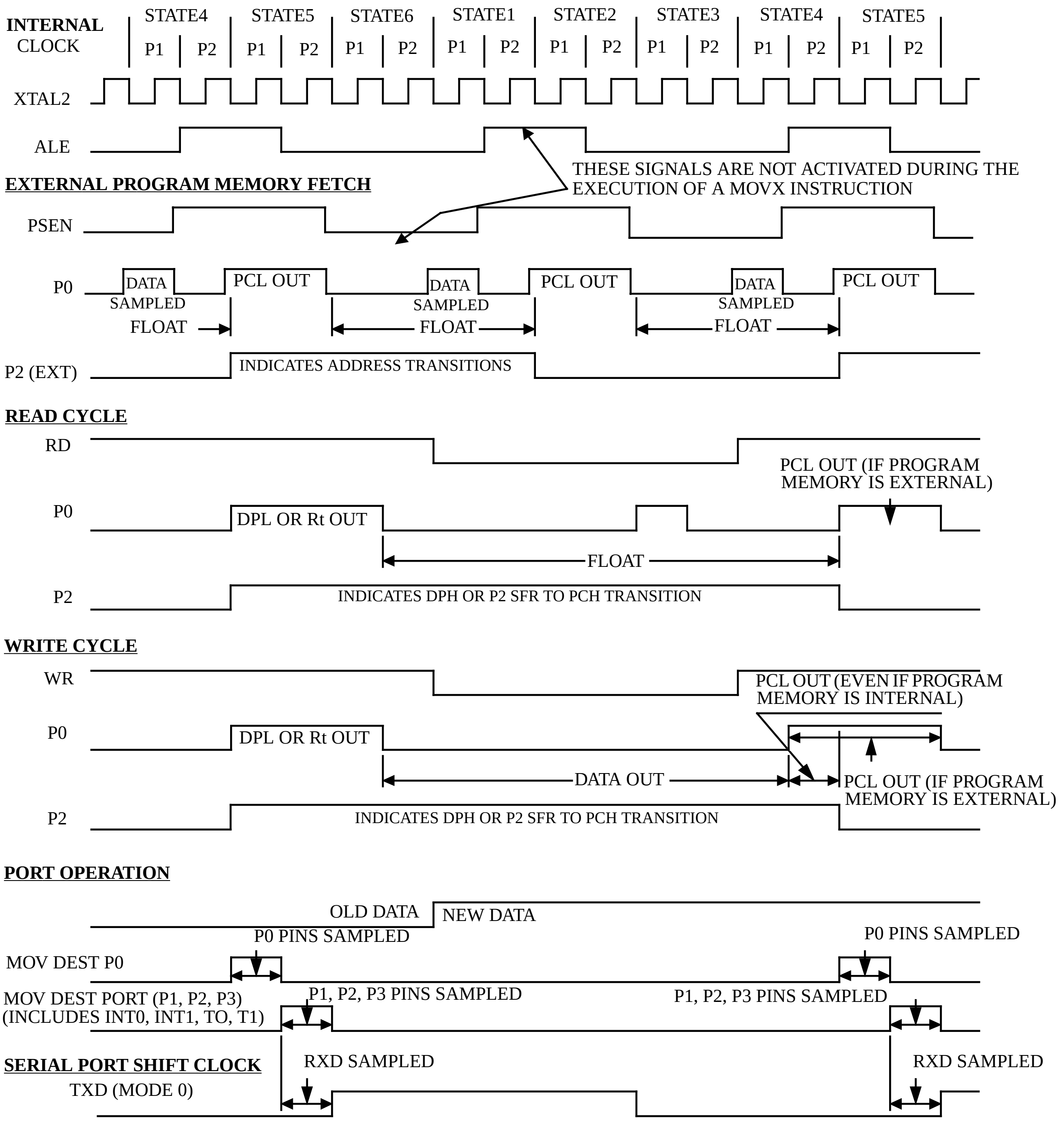


Figure 33. Clock Waveforms

This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though (T_A=25°C fully loaded) $\overline{RD}$ and $\overline{WR}$ propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.